



Preliminary Program Outline

Tuesday December 2nd

17:00 Lab Tours Fraunhofer ENAS Chemnitz

Fraunhofer ENAS

18:00 Welcome reception

Wednesday December 3rd

09:00 **Welcome and Opening**

09:30 **Fundamentals of Wafer Bonding**

11:00 **Activation of Wafer Bonding Surfaces**

12:00 Lunch

Conference
Hotel

13:00 **Silicon Science Award Ceremony**

13:30 **Poster Pitch Session**

15:00 **Glass Wafer Bonding**

all day Poster and Technical Exhibition

17:00 Visit exhibition at the smac Museum

smac Museum

18:00 Social Event - Dinner

Thursday December 4th

09:30 **Characterization and Metrology**

11:00 **3D-Integration by Wafer Bonding**

12:00 Lunch

Conference
Hotel

13:00 **Technology Integration of Wafer Bonding Processes**

14:30 **Die to Wafer Bonding Techniques**

15:45 **Closing Remarks**

all day Poster and Technical Exhibition